# **2SC2377** Silicon NPN epitaxial planar type

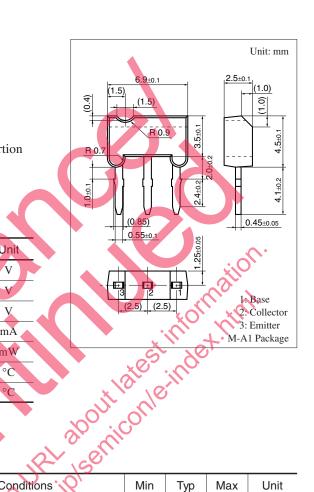
For high-frequency amplification

#### Features

- Optimum for RF amplification of FM/AM radios
- $\bullet$  High transition frequency  $f_{\rm T}$
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	30	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	3	V
Collector current	I <sub>C</sub>	15	mA
Collector power dissipation	P <sub>C</sub>	200	mW
Junction temperature	Tj	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

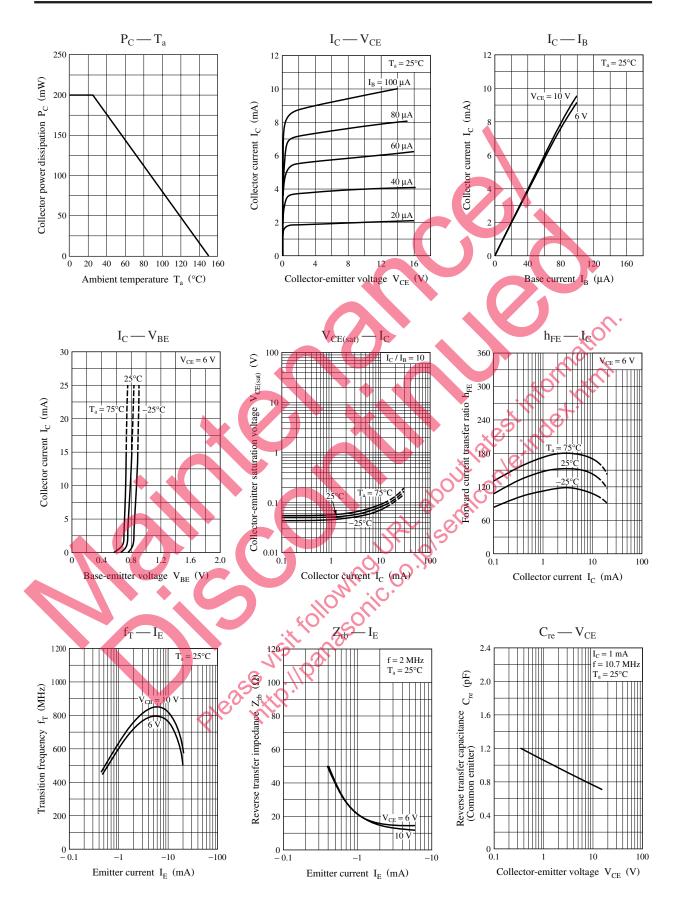


### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

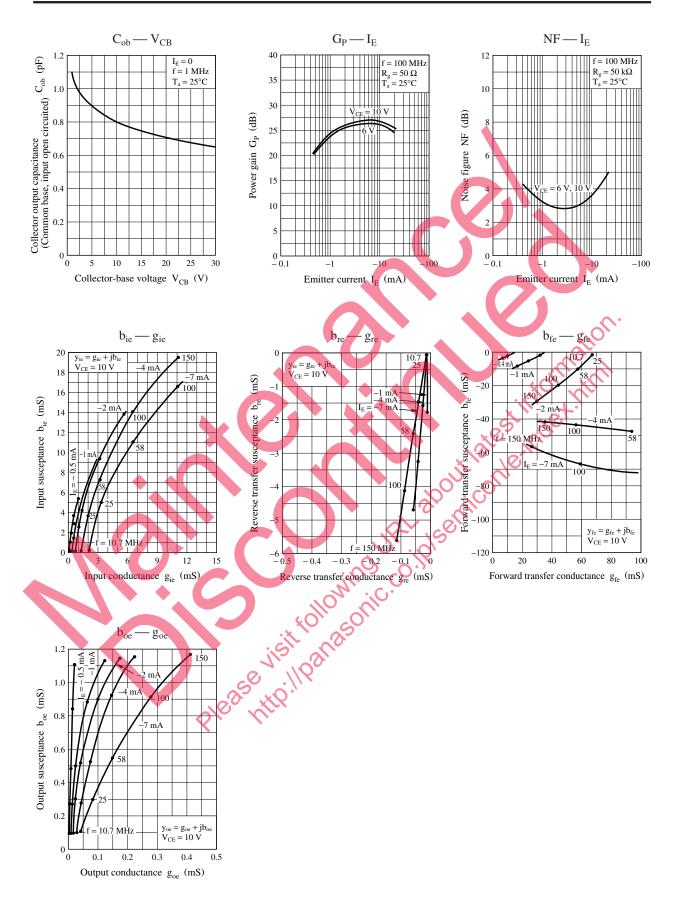
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Base-emitter voltage	V <sub>BE</sub>	$V_{CB} = 6 \text{ V}, 1_{E} = -1 \text{ mA}$		720		mV
Collector-base cutoff current (Emitter open)	Ісво	$V_{CB} = 10$ V, $I_E = 0$			100	nA
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{CE} = 20 \text{ V}, I_{B} = 0$			10	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = 3 V_{2} I_{C} = 0$			1	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CB} = 6$ V, $I_E = -1$ mA	65		260	
Transition frequency	F	$V_{GB} = 6 \text{ V}, I_E = -1 \text{ mA}, f = 100 \text{ MHz}$	450	650		MHz
Noise figure	NF	$V_{CB} = 6 \text{ V}, \text{ I}_{E} = -1 \text{ mA}, \text{ f} = 100 \text{ MHz}$		3.3	5.0	dB
Power gain	GR	$V_{CB} = 6 V, I_E = -1 mA, f = 100 MHz$	20	24		dB
Reverse transfer capacitance	C <sub>re</sub>	$V_{CB} = 6 V, I_E = -1 mA, f = 10.7 MHz$		0.8	1.0	pF
(Common emitter)						

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. \*: Rank classification

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	Rank	С	D
	$h_{FE}$	65 to 160	100 to 260



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